Product data sheet

1. General description

WG30N65UAW1 uses advanced Fine Trench Field-stop IGBT technology with anti-parallel diode in TO247 package to provide extremely low Vce(sat), and excellent switching performance. This device offers Best-in-Class efficiency in hard switching and resonant topology.





2. Features and benefits

- · Maximum junction temperature 175 °C
- · Positive Temperature efficient for easy paralleling
- · Very soft, fast recovery anti-parallel diode
- · High switching speed
- · EMI Improved Design

3. Applications

- PFC
- Solar converters
- UPS
- Welding Converters
- · Mid to high range switching frequency converters

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter		Notes		Value		Unit
V _{CE}	Collector-emitter voltage, $T_j \ge 2$	Collector-emitter voltage, T _j ≥ 25 °C			650		
I _C	DC collector current, limited by $T_{j(max)}$ $T_C = 100~^{\circ}C$				30		Α
Symbol	Parameter Conditions		Notes	Min	Тур	Max	Unit
Static cha	Static characteristics						
V _{CE(sat)}	Collector-emitter saturation voltage	$V_{GE} = 15 \text{ V}; I_{C} = 30 \text{ A}; T_{j} = 25 \text{ °C}$		-	1.45	1.9	V

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate		•C
2	С	collector		
3	E	emitter		
mb	С	mounting base; connected to collector	TO247	G E sym200

6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WG30N65UAW1	TO247	WG30N65UAW1Q	Tube	30	TO247P	09-Mar-2023

7. Marking

Table 4. Marking codes

Type number	Marking codes
WG30N65UAW1	G30N65 UAW1

8. Limiting values

Table 5. Limiting values

Symbol	Parameter	Notes	Value	Unit
V _{CE}	Collector-emitter voltage, T _j ≥ 25 °C		650	V
I _C	DC collector current, limited by $T_{j(max)}$ T_{c} = 25 °C T_{c} = 100 °C		60 30	А
I _{C(puls)}	Pulsed collector current, t _p limited by T _{j(max)}		90	А
-	Turn off safe operating area $V_{CE} \le 650 \text{ V}, T_j \le 175 ^{\circ}\text{C}, t_p = 1 \mu\text{s}$		90	А
I _F	Diode forward current, limited by $T_{j(max)}$ T_{c} = 25 °C T_{c} = 100 °C		20 10	А
I _{Fpuls}	Diode pulsed current, t _p limited by T _{j(max)}		40	Α
V_{GE}	Gate-emitter voltage		±20	V
P _{tot}	Power dissipation $T_C = 25 ^{\circ}\text{C}$ Power dissipation $T_C = 100 ^{\circ}\text{C}$		312 156	W
T _{stg}	Storage temperature		-55 to +150	°C
T _{jmax}	Maximum operating junction temperature		175	°C
-	Peak soldering temperture		260	°C
M	Mounting Torque with washer		0.55	Nm

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
R _{th(j-c)}	IGBT thermal resistance from junction to case			-	0.48	-	K/W
R _{th(j-c)}	Diode thermal resistance from junction to case			-	2	-	K/W
R _{th(j-a)}	thermal resistance from junction to ambient			-	40	-	K/W

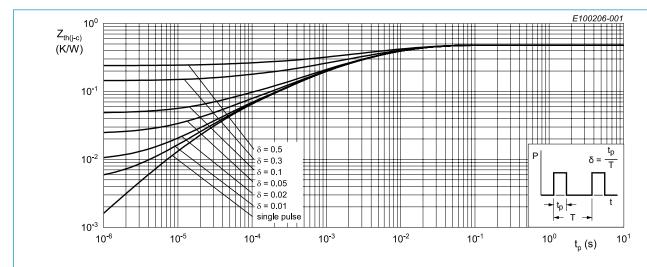


Fig. 1. Transient thermal impedance from junction to case as a function of pulse duration; IGBT

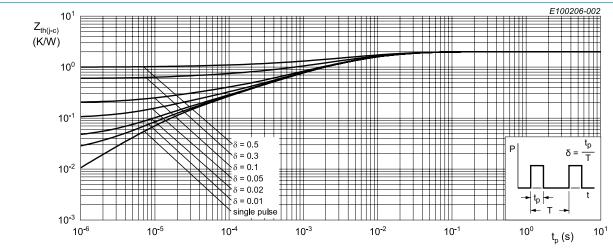


Fig. 2. Transient thermal impedance from junction to case as a function of pulse duration; Diode

10. Characteristics

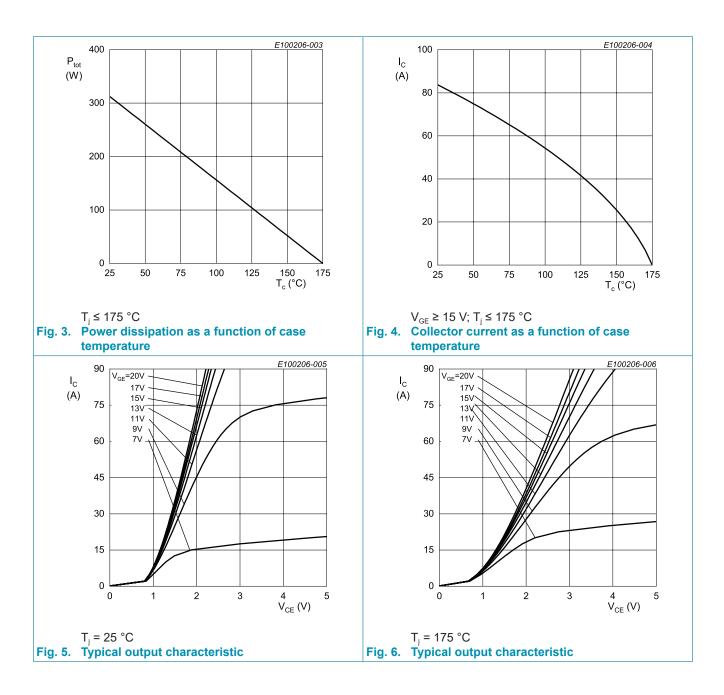
Table 7. Characteristics

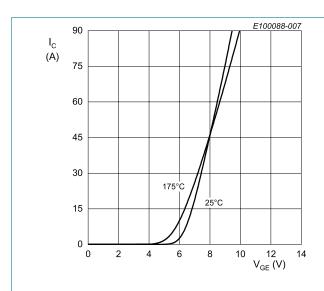
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static cha	aracteristics				,		
BV_CES	Collector-emitter breakdown voltage	$V_{GE} = 0 \text{ V}; I_{C} = 1.0 \text{ mA}$		650	-	-	V
$V_{\text{CE(sat)}}$	Collector-emitter saturation	$V_{GE} = 15 \text{ V}; I_{C} = 30 \text{ A}; T_{j} = 25 \text{ °C}$		-	1.45	1.9	V
	voltage	V_{GE} = 15 V; I_{C} = 30 A; T_{j} = 175 °C		-	1.8	-	V
V _F	Diode forward voltage	$V_{GE} = 0 \text{ V}; I_F = 10 \text{ A}; T_j = 25 \text{ °C}$		-	1.9	-	V
		V _{GE} = 0 V; I _F = 10 A; T _j = 175 °C		-	1.45	-	V
$V_{\text{GE(th)}}$	Gate-emitter threhold voltage	$I_{\rm C}$ = 0.6 mA; $V_{\rm CE}$ = $V_{\rm GE}$		3.6	4.5	5.4	V
I _{CES}	Zero gate voltage collector current	$V_{CE} = 650 \text{ V}; V_{GE} = 0 \text{ V}; T_j = 25 \text{ °C}$		-	-	100	μA
		$V_{CE} = 650 \text{ V}; V_{GE} = 0 \text{ V}; T_j = 175 ^{\circ}\text{C}$		-	-	1	mA
g _{fs}	Transconductance	V _{CE} = 20 V; I _C = 30 A		-	28	-	S
Dynamic	characteristics						
C _{ies}	Input capacitance	$V_{CE} = 30 \text{ V}; V_{GE} = 0 \text{ V}; f = 1 \text{ MHz};$		-	1591	-	pF
C _{oes}	Output capacitance	T _j = 25 °C		-	58	-	pF
C _{res}	Reverse transfer capacitance			-	17	-	pF
Q_{G}	Gate charge	V_{CC} = 520 V; I_{C} = 30 A; V_{GE} = 15 V; T_{j} = 25 °C		-	72	-	nC

11. Switching Characteristics

Table 8. Switching Characteristics, Inductive Load

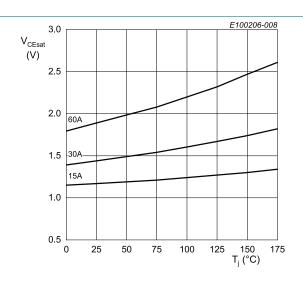
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
IGBT cha	racteristics						
$t_{d(on)}$	Turn-on delay time	T _j = 25 °C;		-	29	-	nS
t _r	Rise time	$V_{CC} = 400 \text{ V}; I_C = 30 \text{ A}; V_{GE} = 15 \text{V} / 0 \text{V};$ $R_G = 10 \Omega$		-	29	-	nS
$t_{\text{d(off)}}$	Turn-off delay time			-	127	-	nS
t _f	Fall time			-	37	-	nS
E _{on}	Turn-on energy			-	0.52	-	mJ
E _{off}	Turn-off energy			-	0.33	-	mJ
E _{ts}	Total switching energy			-	0.85	-	mJ
t _{d(on)}	Turn-on delay time	$T_{j} = 175 ^{\circ}\text{C};$ $V_{CC} = 400 \text{V}; I_{C} = 30 \text{A}; V_{GE} = 15 \text{V} / 0 \text{V};$ $R_{G} = 10 \Omega$		-	27	-	nS
t _r	Rise time			-	28	-	nS
$t_{\text{d(off)}}$	Turn-off delay time			-	150	-	nS
t _f	Fall time			-	44	-	nS
E _{on}	Turn-on energy			-	0.75	-	mJ
E _{off}	Turn-off energy			-	0.49	-	mJ
E _{ts}	Total switching energy			-	1.24	-	mJ
Diode cha	aracteristics		ı				
t _{rr}	Reverse recovery time	T _j = 25 °C;		-	32	-	nS
Q _r	Reverse recovery charge	$\dot{V}_R = 400 \text{ V}; I_F = 10 \text{ A}; dI_F/dt = 500 \text{A/us}$		-	148	-	nC
I _{RM}	Reverse recovery peak current			-	8	-	А
t _{rr}	Reverse recovery time	$T_j = 175 ^{\circ}\text{C};$ $V_R = 400 ^{\circ}\text{V}; I_F = 10 ^{\circ}\text{A}; dI_F/dt = 500 ^{\circ}\text{A/us}$		-	71	-	nS
Q _r	Reverse recovery charge			-	508	-	nC
I _{RM}	Reverse recovery peak current			-	12	-	А





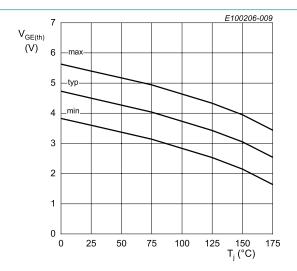
 $V_{CE} = 20 \text{ V}$

Fig. 7. Typical transfer characteristic



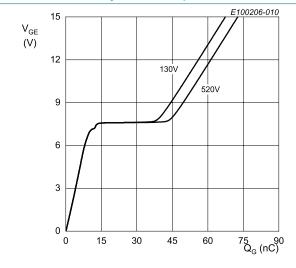
 $V_{GE} = 15 V$

Fig. 8. Typical collector-emitter saturation voltage as a function of junction temperature



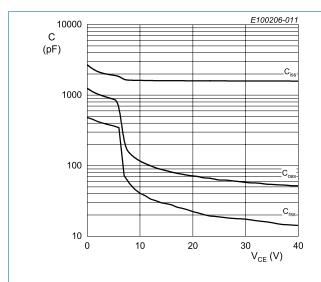
 $I_{c} = 600 \, \mu A$

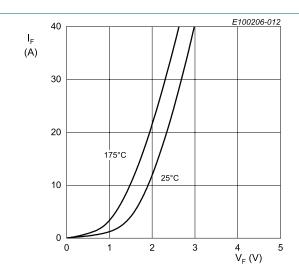
Fig. 9. Gate-emitter threshold voltage as a function of junction temperature



 $I_{c} = 30 \text{ A}$

Fig. 10. Typical gate charge

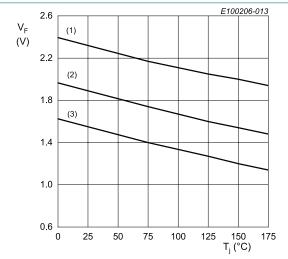


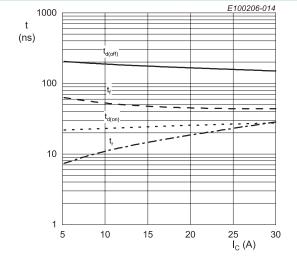


 $V_{GE} = 0 \text{ V; } f = 1 \text{ MHz}$

Fig. 12. Typical diode forward current as a function of forward voltage







(1) $I_F = 20 A$ (2) $I_F = 10 A$

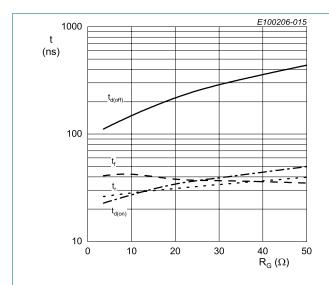
 $(3) I_F = 5 A$

 R_g = 10 Ω ; V_{GE} = 15V/0V; T_j = 175 °C; V_{CE} = 400 V; inductive load

Fig. 13. Typical diode forward voltage as a function of junction temperature

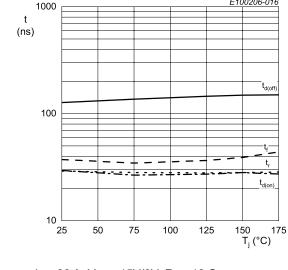
Fig. 14. Typical switching times as a function of collector current

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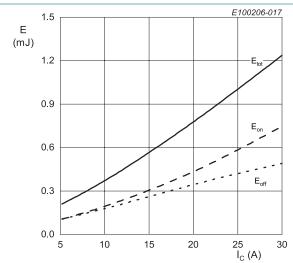
 $I_C = 30 \text{ A}; V_{GE} = 15 \text{V/0V}; T_i = 175 °C;$ V_{CE} = 400 V; inductive load

Fig. 15. Typical switching times as a function of gate resistance



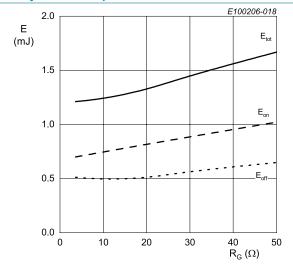
 I_{C} = 30 A; V_{GE} = 15V/0V; R_{q} = 10 Ω ; V_{CE} = 400 V; inductive load

Fig. 16. Typical switching times as a function of junction temperature



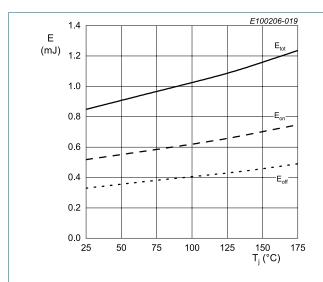
 R_{g} = 10 $\Omega;$ V_{GE} = 15V/0V; T_{j} = 175 °C; V_{CE} = 400 V; inductive load

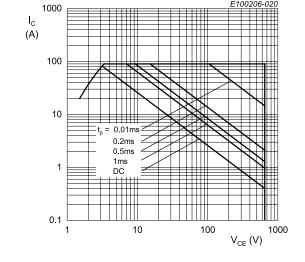
Fig. 17. Typical switching energy losses as a function of collector current



 I_{C} = 30 A; V_{GE} = 15V/0V; T_{j} = 175 °C; V_{CE} = 400 V; inductive load

Fig. 18. Typical switching energy losses as a function of gate resistance





 I_{C} = 30 A; V_{GE} = 15V/0V; R_{g} = 10 $\Omega;$ V_{CE} = 400 V; inductive load

Fig. 20. Forward bias safe operating area

Fig. 19. Typical switching energy losses as a function of junction temperature

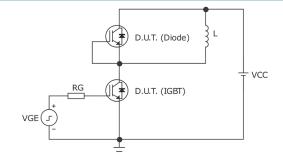


Fig. 21. Test circuit for inductive load switching

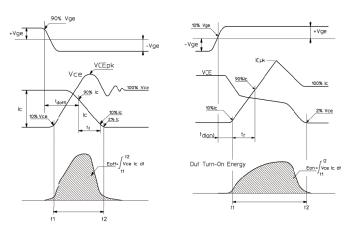
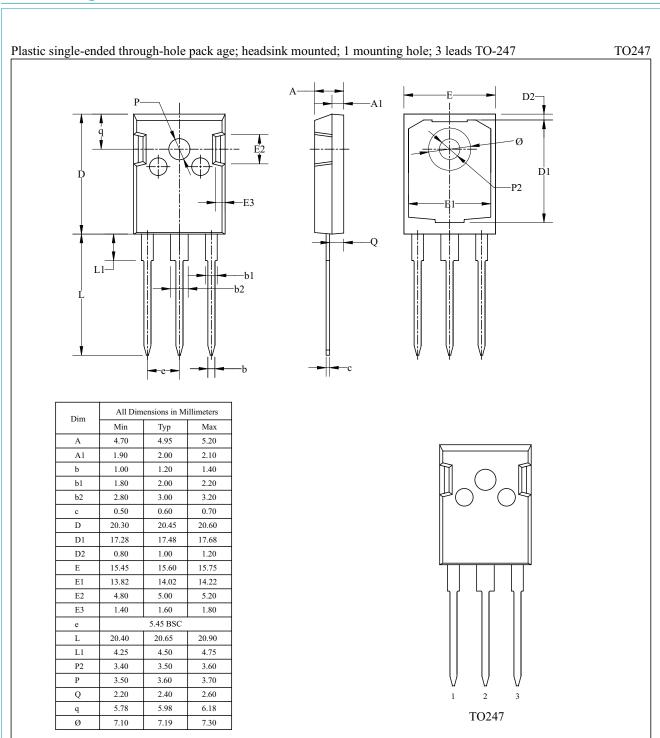


Fig. 22. Definition of switching times and losses

12. Package outline



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13. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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